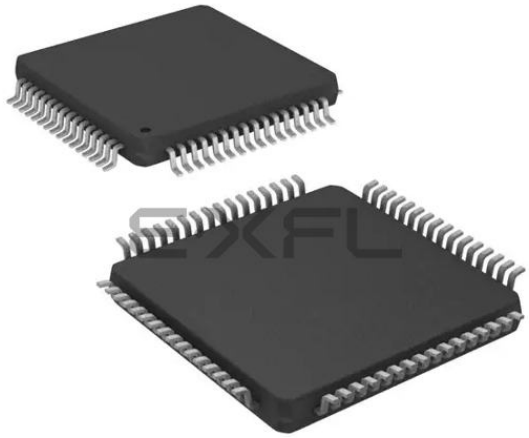

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f65j10t-i-pt

3.5 Internal Oscillator Block

The PIC18F87J10 family of devices includes an internal oscillator source (INTRC) which provides a nominal 31 kHz output. The INTRC is enabled on device power-up and clocks the device during its configuration cycle until it enters operating mode. INTRC is also enabled if it is selected as the device clock source or if any of the following are enabled:

- Fail-Safe Clock Monitor
- Watchdog Timer
- Two-Speed Start-up

These features are discussed in greater detail in **Section 24.0 "Special Features of the CPU"**.

The INTRC can also be optionally configured as the default clock source on device start-up by setting the FOSC2 Configuration bit. This is discussed in **Section 3.6.1 "Oscillator Control Register"**.

3.6 Clock Sources and Oscillator Switching

The PIC18F87J10 family includes a feature that allows the device clock source to be switched from the main oscillator to an alternate clock source. PIC18F87J10 family devices offer two alternate clock sources. When an alternate clock source is enabled, the various power-managed operating modes are available.

Essentially, there are three clock sources for these devices:

- Primary oscillators
- Secondary oscillators
- Internal oscillator

The **primary oscillators** include the External Crystal and Resonator modes and the External Clock modes. The particular mode is defined by the FOSC<2:0> Configuration bits. The details of these modes are covered earlier in this chapter.

The **secondary oscillators** are those external sources not connected to the OSC1 or OSC2 pins. These sources may continue to operate even after the controller is placed in a power-managed mode.

PIC18F87J10 family devices offer the Timer1 oscillator as a secondary oscillator. This oscillator, in all power-managed modes, is often the time base for functions such as a real-time clock.

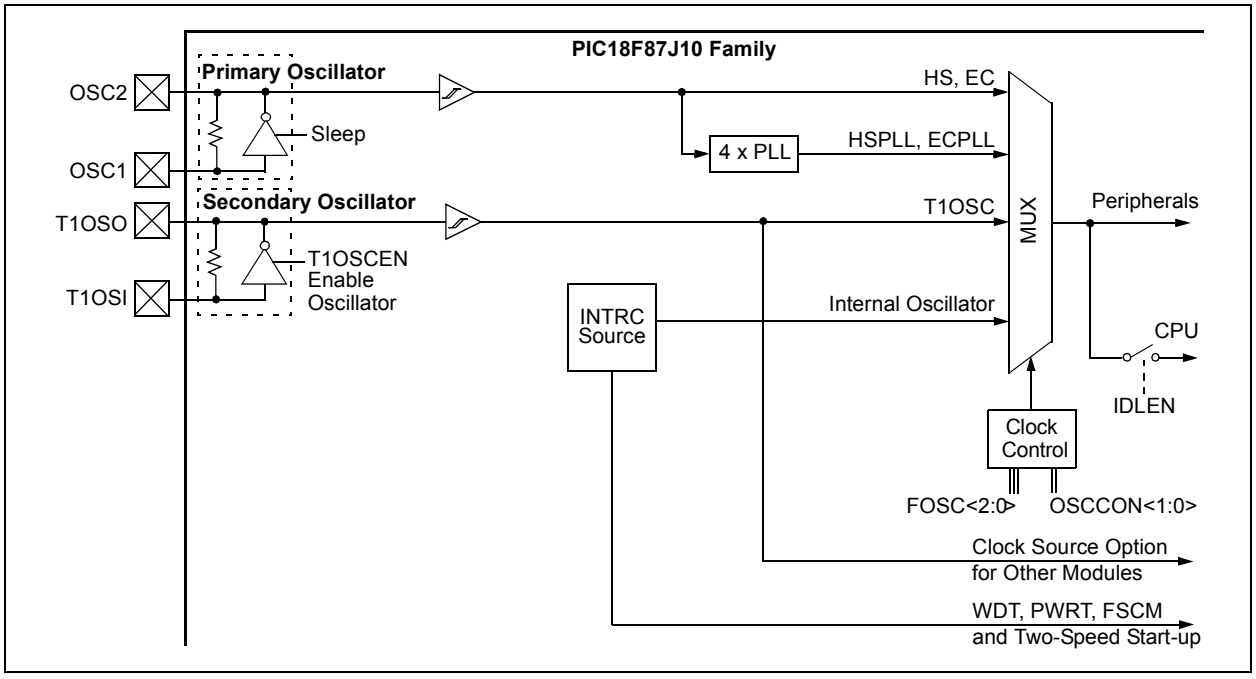
Most often, a 32.768 kHz watch crystal is connected between the RC0/T1OSO/T13CKI and RC1/T1OSI pins. Loading capacitors are also connected from each pin to ground.

The Timer1 oscillator is discussed in greater detail in **Section 13.3 "Timer1 Oscillator"**.

In addition to being a primary clock source, the **internal oscillator** is available as a power-managed mode clock source. The INTRC source is also used as the clock source for several special features, such as the WDT and Fail-Safe Clock Monitor.

The clock sources for the PIC18F87J10 family devices are shown in Figure 3-5. See **Section 24.0 "Special Features of the CPU"** for Configuration register details.

FIGURE 3-5: PIC18F87J10 FAMILY CLOCK DIAGRAM



6.2 PIC18 Instruction Cycle

6.2.1 CLOCKING SCHEME

The microcontroller clock input, whether from an internal or external source, is internally divided by four to generate four non-overlapping quadrature clocks (Q1, Q2, Q3 and Q4). Internally, the program counter is incremented on every Q1; the instruction is fetched from the program memory and latched into the instruction register during Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 6-5.

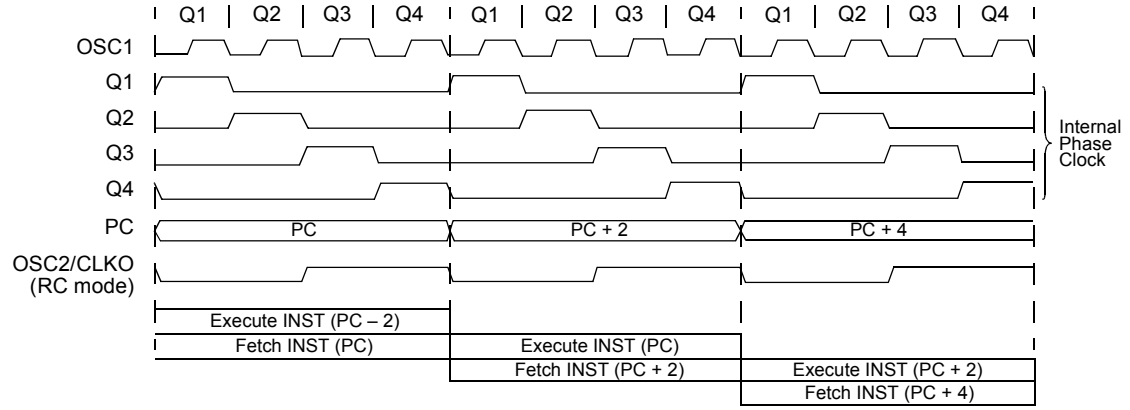
6.2.2 INSTRUCTION FLOW/PIPELINING

An “Instruction Cycle” consists of four Q cycles, Q1 through Q4. The instruction fetch and execute are pipelined in such a manner that a fetch takes one instruction cycle, while the decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., `GOTO`), then two cycles are required to complete the instruction (Example 6-3).

A fetch cycle begins with the Program Counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 6-5: CLOCK/INSTRUCTION CYCLE

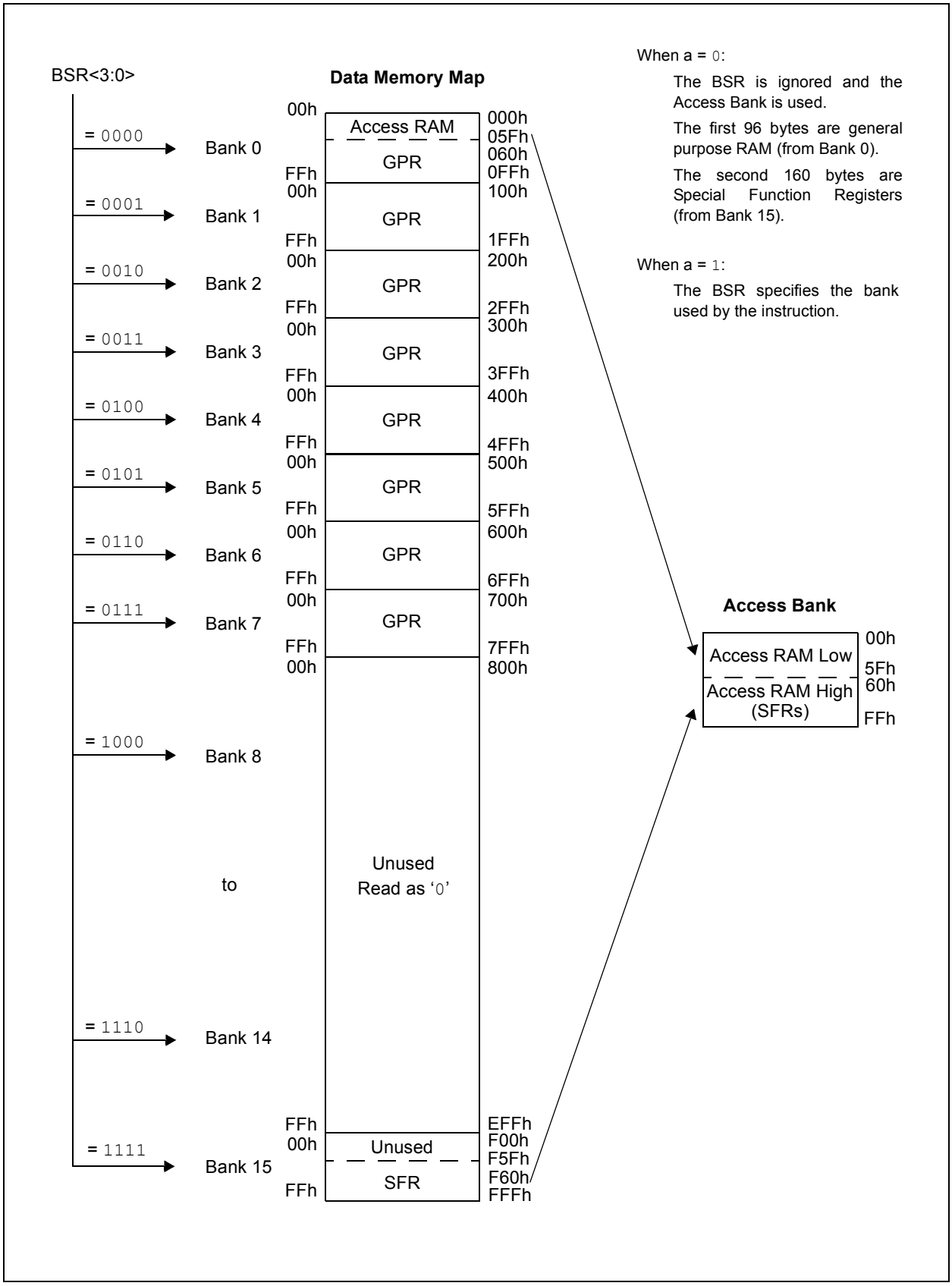


EXAMPLE 6-3: INSTRUCTION PIPELINE FLOW

	TCY0	TCY1	TCY2	TCY3	TCY4	TCY5
1. MOVLW 55h	Fetch 1	Execute 1				
2. MOVWF PORTB		Fetch 2	Execute 2			
3. BRA SUB_1			Fetch 3	Execute 3		
4. BSF PORTA, BIT3 (Forced NOP)				Fetch 4	Flush (NOP)	
5. Instruction @ address SUB_1					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline while the new instruction is being fetched and then executed.

FIGURE 6-7: DATA MEMORY MAP FOR PIC18FX5J10/X5J15/X6J10 DEVICES



10.4 IPR Registers

The IPR registers contain the individual priority bits for the peripheral interrupts. Due to the number of peripheral interrupt sources, there are three Peripheral Interrupt Priority registers (IPR1, IPR2, IPR3). Using the priority bits requires that the Interrupt Priority Enable (IPEN) bit be set.

REGISTER 10-10: IPR1: PERIPHERAL INTERRUPT PRIORITY REGISTER 1

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
PSPIP	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **PSPIP:** Parallel Port Read/Write Interrupt Priority bit
1 = High priority
0 = Low priority

bit 6 **ADIP:** A/D Converter Interrupt Priority bit
1 = High priority
0 = Low priority

bit 5 **RC1IP:** EUSART1 Receive Interrupt Priority bit
1 = High priority
0 = Low priority

bit 4 **TX1IP:** EUSART1 Transmit Interrupt Priority bit
1 = High priority
0 = Low priority

bit 3 **SSP1IP:** Master Synchronous Serial Port 1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 2 **CCP1IP:** ECCP1 Interrupt Priority bit
1 = High priority
0 = Low priority

bit 1 **TMR2IP:** TMR2 to PR2 Match Interrupt Priority bit
1 = High priority
0 = Low priority

bit 0 **TMR1IP:** TMR1 Overflow Interrupt Priority bit
1 = High priority
0 = Low priority

17.1 CCP Module Configuration

Each Capture/Compare/PWM module is associated with a control register (generically, CCPxCON) and a data register (CCPRx). The data register, in turn, is comprised of two 8-bit registers: CCPRxL (low byte) and CCPRxH (high byte). All registers are both readable and writable.

17.1.1 CCP MODULES AND TIMER RESOURCES

The CCP/ECCP modules utilize Timers 1, 2, 3 or 4, depending on the mode selected. Timer1 and Timer3 are available to modules in Capture or Compare modes, while Timer2 and Timer4 are available for modules in PWM mode.

TABLE 17-1: CCP MODE – TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1 or Timer3
Compare	Timer1 or Timer3
PWM	Timer2 or Timer4

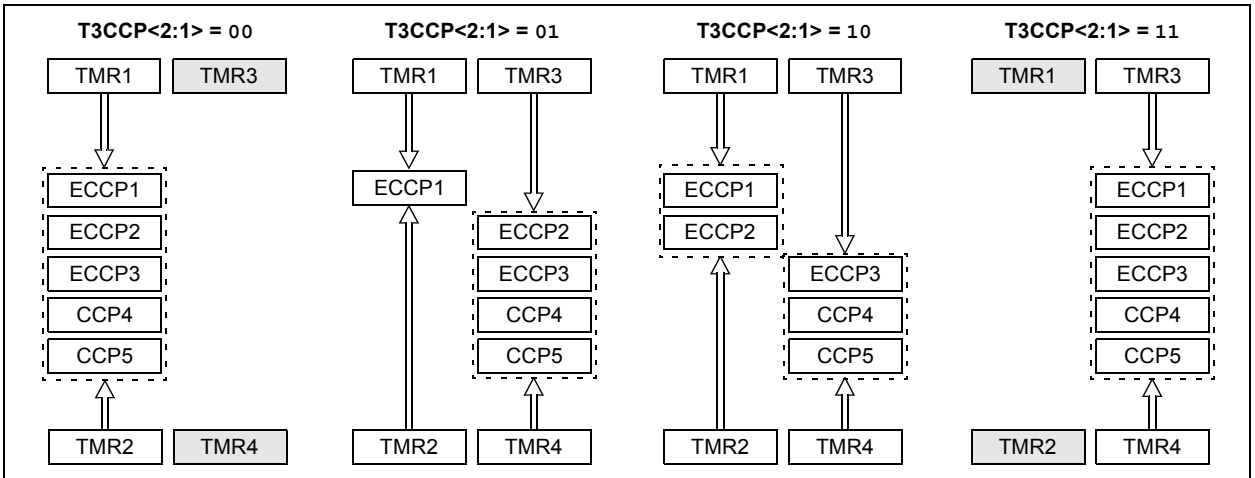
The assignment of a particular timer to a module is determined by the Timer to CCP enable bits in the T3CON register (Register 15-1, page 163). Depending on the configuration selected, up to four timers may be active at once, with modules in the same configuration (capture/compare or PWM) sharing timer resources. The possible configurations are shown in Figure 17-1.

17.1.2 ECCP2 PIN ASSIGNMENT

The pin assignment for ECCP2 (capture input, compare and PWM output) can change, based on device configuration. The CCP2MX Configuration bit determines which pin ECCP2 is multiplexed to. By default, it is assigned to RC1 (CCP2MX = 1). If the Configuration bit is cleared, ECCP2 is multiplexed with RE7 on 64-pin devices and RB3 or RE7 on 80-pin devices depending on mode setting.

Changing the pin assignment of ECCP2 does not automatically change any requirements for configuring the port pin. Users must always verify that the appropriate TRIS register is configured correctly for ECCP2 operation regardless of where it is located.

FIGURE 17-1: CCP/ECCP AND TIMER INTERCONNECT CONFIGURATIONS



Timer1 is used for all capture and compare operations for all CCP modules. Timer2 is used for PWM operations for all CCP modules. Modules may share either timer resource as a common time base.

Timer3 and Timer4 are not available.

Timer1 and Timer2 are used for capture and compare or PWM operations for ECCP1 only (depending on selected mode).

All other modules use either Timer3 or Timer4. Modules may share either timer resource as a common time base if they are in capture/compare or PWM modes.

Timer1 and Timer2 are used for capture and compare or PWM operations for ECCP1 and ECCP2 only (depending on the mode selected for each module). Both modules may use a timer as a common time base if they are both in capture/compare or PWM modes.

The other modules use either Timer3 or Timer4. Modules may share either timer resource as a common time base if they are in capture/compare or PWM modes.

Timer3 is used for all capture and compare operations for all CCP modules. Timer4 is used for PWM operations for all CCP modules. Modules may share either timer resource as a common time base.

Timer1 and Timer2 are not available.

TABLE 17-2: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, TIMER1 AND TIMER3

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	53
RCON	IPEN	—	—	$\overline{RI}$	$\overline{TO}$	$\overline{PD}$	$\overline{POR}$	$\overline{BOR}$	54
PIR1	PSPIF	ADIF	RC1IF	TX1IF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	55
PIE1	PSPIE	ADIE	RC1IE	TX1IE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	55
IPR1	PSPIP	ADIP	RC1IP	TX1IP	SSP1IP	CCP1IP	TMR2IP	TMR1IP	55
PIR2	OSCFIF	CMIF	—	—	BCL1IF	—	TMR3IF	CCP2IF	55
PIE2	OSCFIE	CMIE	—	—	BCL1IE	—	TMR3IE	CCP2IE	55
IPR2	OSCFIP	CMIP	—	—	BCL1IP	—	TMR3IP	CCP2IP	55
PIR3	SSP2IF	BCL2IF	RC2IF	TX2IF	TMR4IF	CCP5IF	CCP4IF	CCP3IF	55
PIE3	SSP2IE	BCL2IE	RC2IE	TX2IE	TMR4IE	CCP5IE	CCP4IE	CCP3IE	55
IPR3	SSP2IP	BCL2IP	RC2IP	TX2IP	TMR4IP	CCP5IP	CCP4IP	CCP3IP	55
TRISG	—	—	—	TRISG4	TRISG3	TRISG2	TRISG1	TRISG0	56
TMR1L	Timer1 Register Low Byte								54
TMR1H	Timer1 Register High Byte								54
T1CON	RD16	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	54
TMR3H	Timer3 Register High Byte								55
TMR3L	Timer3 Register Low Byte								55
T3CON	RD16	T3CCP2	T3CKPS1	T3CKPS0	T3CCP1	$\overline{T3SYNC}$	TMR3CS	TMR3ON	55
CCPR4L	Capture/Compare/PWM Register 4 Low Byte								57
CCPR4H	Capture/Compare/PWM Register 4 High Byte								57
CCPR5L	Capture/Compare/PWM Register 5 Low Byte								57
CCPR5H	Capture/Compare/PWM Register 5 High Byte								57
CCP4CON	—	—	DC4B1	DC4B0	CCP4M3	CCP4M2	CCP4M1	CCP4M0	57
CCP5CON	—	—	DC5B1	DC5B0	CCP5M3	CCP5M2	CCP5M1	CCP5M0	57

Legend: — = unimplemented, read as '0'. Shaded cells are not used by capture/compare, Timer1 or Timer3.

FIGURE 18-2: PWM OUTPUT RELATIONSHIPS (ACTIVE-HIGH STATE)

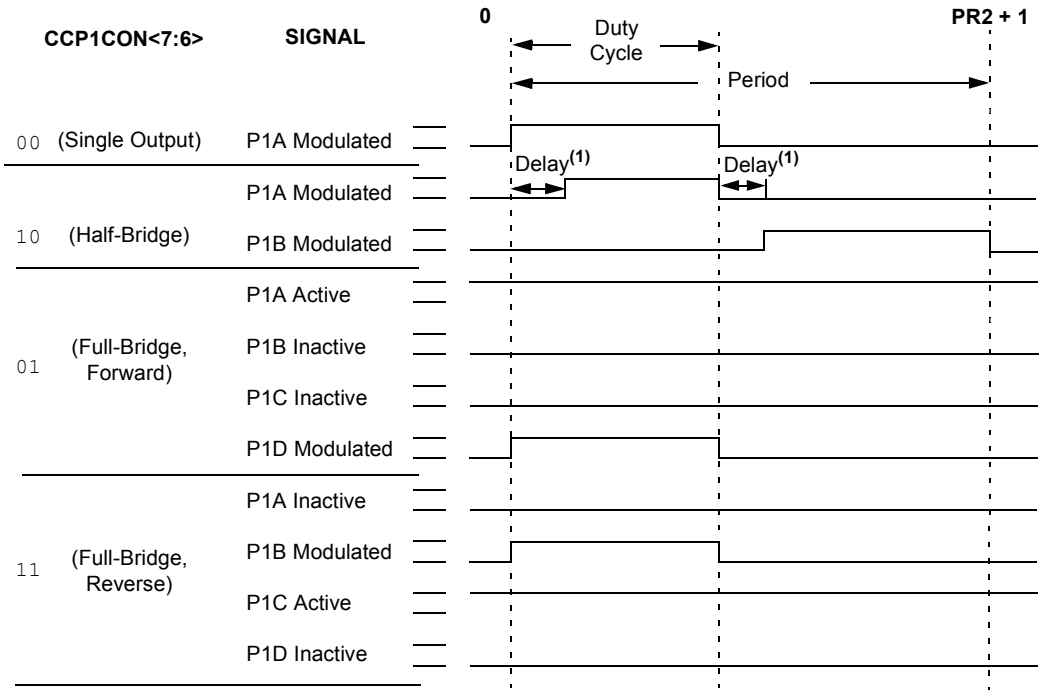
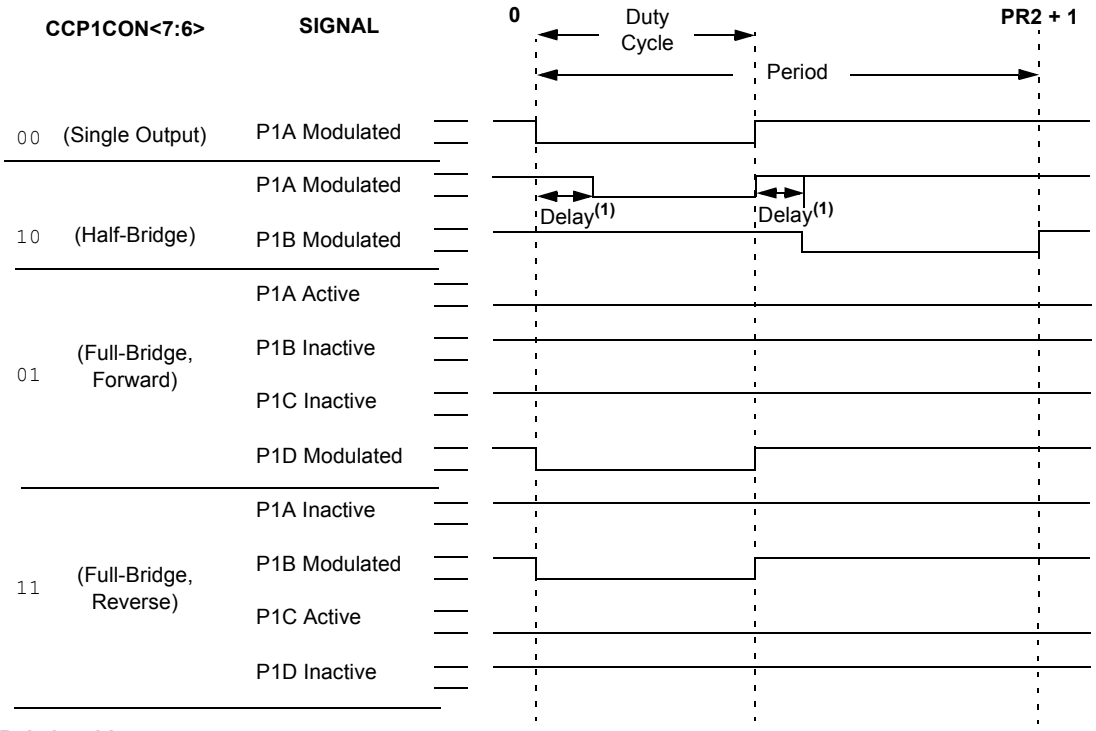


FIGURE 18-3: PWM OUTPUT RELATIONSHIPS (ACTIVE-LOW STATE)



Relationships:

- Period = 4 * TOSC * (PR2 + 1) * (TMR2 Prescale Value)
- Duty Cycle = TOSC * (CCPR1L<7:0>:CCP1CON<5:4>) * (TMR2 Prescale Value)
- Delay = 4 * TOSC * (ECCP1DEL<6:0>)

Note 1: The dead-band delay is programmed using the ECCP1DEL register (**Section 18.4.6 "Programmable Dead-Band Delay"**).

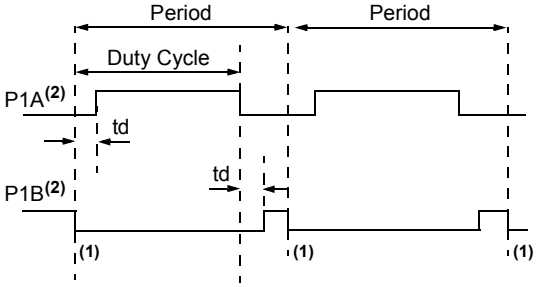
18.4.4 HALF-BRIDGE MODE

In the Half-Bridge Output mode, two pins are used as outputs to drive push-pull loads. The PWM output signal is output on the P1A pin, while the complementary PWM output signal is output on the P1B pin (Figure 18-4). This mode can be used for half-bridge applications, as shown in Figure 18-5, or for full-bridge applications, where four power switches are being modulated with two PWM signals.

In Half-Bridge Output mode, the programmable dead-band delay can be used to prevent shoot-through current in half-bridge power devices. The value of bits, P1DC<6:0>, sets the number of instruction cycles before the output is driven active. If the value is greater than the duty cycle, the corresponding output remains inactive during the entire cycle. See **Section 18.4.6 "Programmable Dead-Band Delay"** for more details on dead-band delay operations.

Since the P1A and P1B outputs are multiplexed with the PORTC<2> and PORTE<6> data latches, the TRISC<2> and TRISE<6> bits must be cleared to configure P1A and P1B as outputs.

FIGURE 18-4: HALF-BRIDGE PWM OUTPUT

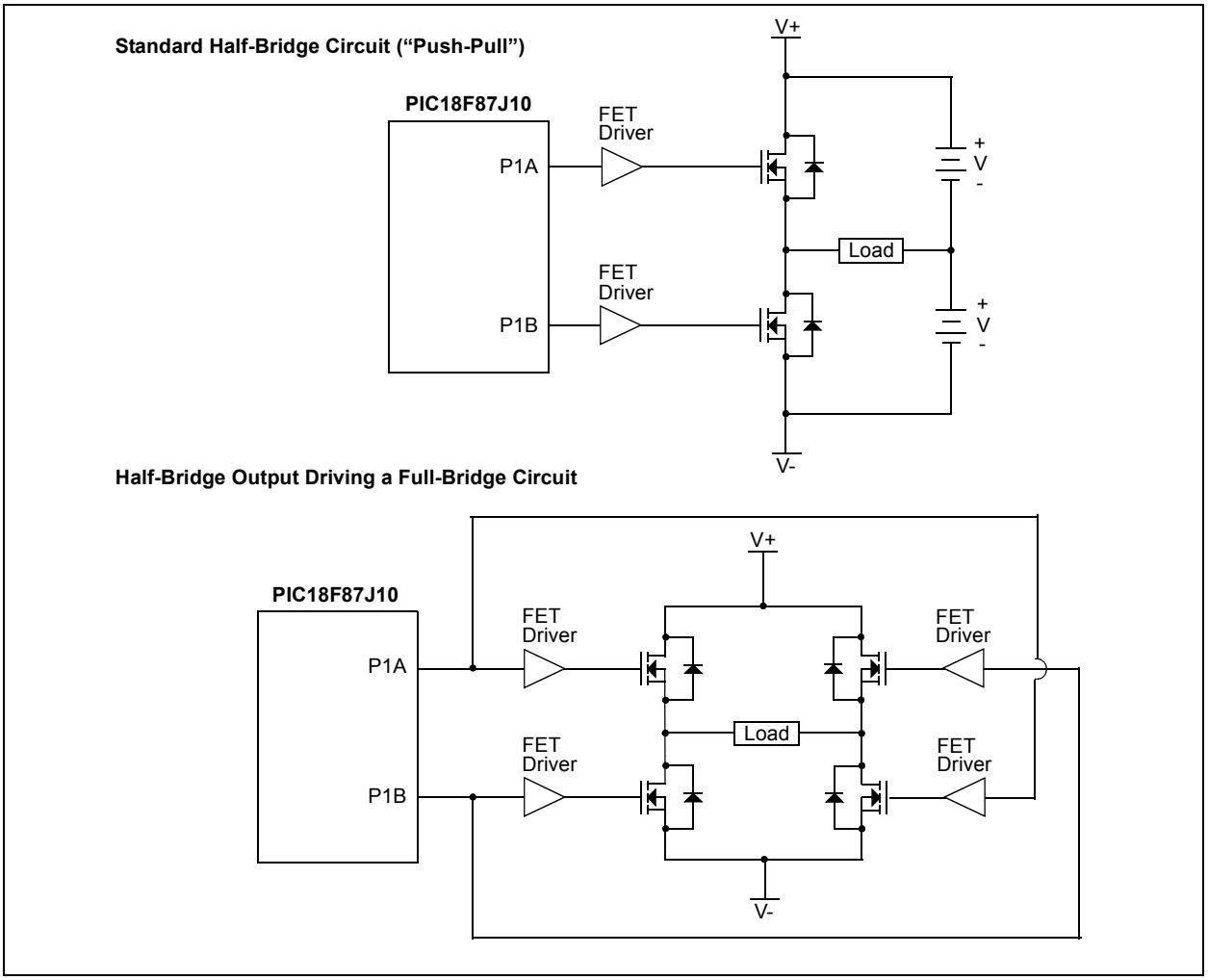


td = Dead Band Delay

Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: The output signals are shown as active-high.

FIGURE 18-5: EXAMPLES OF HALF-BRIDGE OUTPUT MODE APPLICATIONS



REGISTER 19-4: SSPxCON1: MSSPx CONTROL REGISTER 1 (I^2C™ MODE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **WCOL:** Write Collision Detect bit

In Master Transmit mode:
1 = A write to the SSPxBUF register was attempted while the I^2C conditions were not valid for a transmission to be started (must be cleared in software)
0 = No collision

In Slave Transmit mode:
1 = The SSPxBUF register is written while it is still transmitting the previous word (must be cleared in software)
0 = No collision

In Receive mode (Master or Slave modes):
This is a "don't care" bit.

bit 6 **SSPOV:** Receive Overflow Indicator bit

In Receive mode:
1 = A byte is received while the SSPxBUF register is still holding the previous byte (must be cleared in software)
0 = No overflow

In Transmit mode:
This is a "don't care" bit in Transmit mode.

bit 5 **SSPEN:** Master Synchronous Serial Port Enable bit
1 = Enables the serial port and configures the SDAx and SCLx pins as the serial port pins(1)
0 = Disables serial port and configures these pins as I/O port pins(1)

bit 4 **CKP:** SCKx Release Control bit

In Slave mode:
1 = Release clock
0 = Holds clock low (clock stretch); used to ensure data setup time

In Master mode:
Unused in this mode.

bit 3-0 **SSPM<3:0>:** Master Synchronous Serial Port Mode Select bits
1111 = I^2C Slave mode, 10-bit address with Start and Stop bit interrupts enabled(2)
1110 = I^2C Slave mode, 7-bit address with Start and Stop bit interrupts enabled(2)
1011 = I^2C Firmware Controlled Master mode (slave Idle)(2)
1000 = I^2C Master mode, clock = FOSC/(4 * (SSPADD + 1))(2)
0111 = I^2C Slave mode, 10-bit address(2)
0110 = I^2C Slave mode, 7-bit address(2)

Note 1: When enabled, the SDAx and SCLx pins must be properly configured as input or output.
2: Bit combinations not specifically listed here are either reserved or implemented in SPI mode only.

REGISTER 20-2: RCSTAx: RECEIVE STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **SPEN:** Serial Port Enable bit
1 = Serial port enabled (configures RXx/DTx and TXx/CKx pins as serial port pins)
0 = Serial port disabled (held in Reset)

bit 6 **RX9:** 9-Bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5 **SREN:** Single Receive Enable bit
Asynchronous mode:
Don't care.
Synchronous mode – Master:
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.
Synchronous mode – Slave:
Don't care.

bit 4 **CREN:** Continuous Receive Enable bit
Asynchronous mode:
1 = Enables receiver
0 = Disables receiver
Synchronous mode:
1 = Enables continuous receive until enable bit, CREN, is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3 **ADDEN:** Address Detect Enable bit
Asynchronous mode 9-bit (RX9 = 1):
1 = Enables address detection, enables interrupt and loads the receive buffer when RSR<8> is set
0 = Disables address detection, all bytes are received and ninth bit can be used as parity bit
Asynchronous mode 8-bit (RX9 = 0):
Don't care.

bit 2 **FERR:** Framing Error bit
1 = Framing error (can be updated by reading the RCREGx register and receiving the next valid byte)
0 = No framing error

bit 1 **OERR:** Overrun Error bit
1 = Overrun error (can be cleared by clearing bit, CREN)
0 = No overrun error

bit 0 **RX9D:** 9th bit of Received Data
This can be address/data bit or a parity bit and must be calculated by user firmware.

EXAMPLE 20-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

Desired Baud Rate = FOSC/(64 ([SPBRGHx:SPBRGx] + 1))

Solving for SPBRGHx:SPBRGx:

X = ((FOSC/Desired Baud Rate)/64) – 1
= ((16000000/9600)/64) – 1
= [25.042] = 25

Calculated Baud Rate = 16000000/(64 (25 + 1))
= 9615

Error = (Calculated Baud Rate – Desired Baud Rate)/Desired Baud Rate
= (9615 – 9600)/9600 = 0.16%

TABLE 20-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
TXSTAx	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	55
RCSTAx	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	55
BAUDCONx	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	56
SPBRGHx	EUSARTx Baud Rate Generator Register High Byte								56
SPBRGx	EUSARTx Baud Rate Generator Register Low Byte								56

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the BRG.

NOTES:

24.3 On-Chip Voltage Regulator

All of the PIC18F87J10 family devices power their core digital logic at a nominal 2.5V. For designs that are required to operate at a higher typical voltage, such as 3.3V, all devices in the PIC18F87J10 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator is controlled by the ENVREG pin. Tying VDD to the pin enables the regulator, which in turn, provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR filter capacitor must be connected to the VDDCORE/VCAP pin (Figure 24-2). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 27.3 "DC Characteristics: PIC18F87J10 Family (Industrial)"**.

If ENVREG is tied to VSS, the regulator is disabled. In this case, separate power for the core logic at a nominal 2.5V must be supplied to the device on the VDDCORE/VCAP pin to run the I/O pins at higher voltage levels, typically 3.3V. Alternatively, the VDDCORE/VCAP and VDD pins can be tied together to operate at a lower nominal voltage. Refer to Figure 24-2 for possible configurations.

24.3.1 ON-CHIP REGULATOR AND BOR

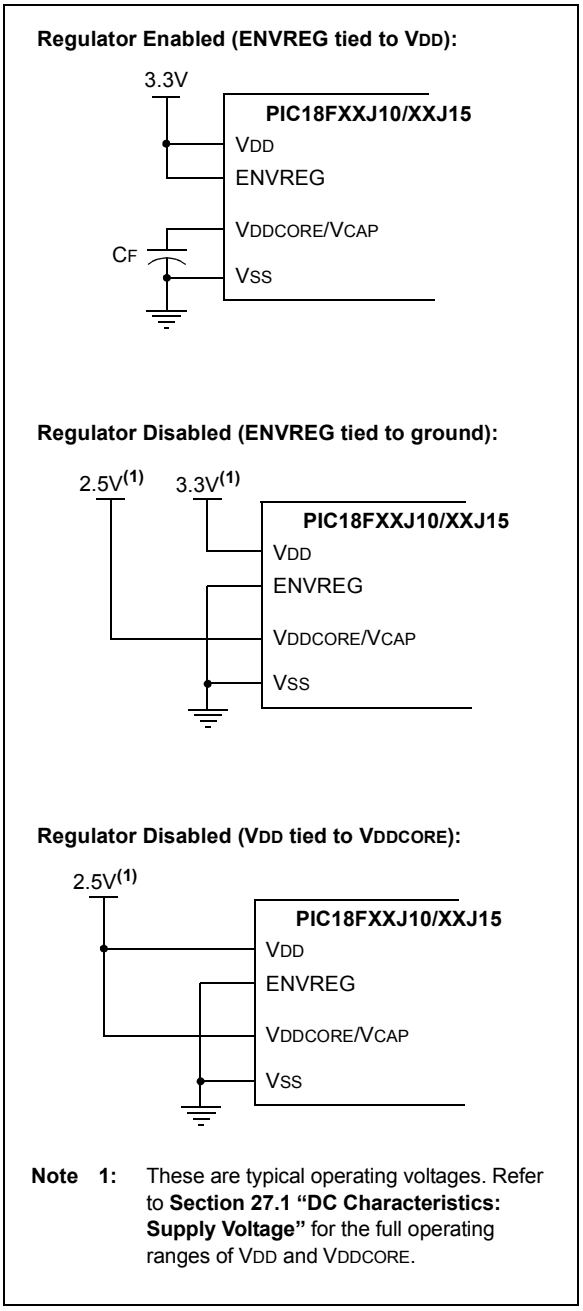
When the on-chip regulator is enabled, PIC18F87J10 family devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a BOR Reset. This event is captured by the BOR flag bit (RCON<0>).

The operation of the BOR is described in more detail in **Section 5.4 "Brown-out Reset (BOR)"** and **Section 5.4.1 "Detecting BOR"**. The brown-out voltage levels are specific in **Section 27.1 "DC Characteristics: Supply Voltage, PIC18F87J10 Family (Industrial)"**.

24.3.2 POWER-UP REQUIREMENTS

The on-chip regulator is designed to meet the power-up requirements for the device. If the application does not use the regulator, then strict power-up conditions must be adhered to. While powering up, VDDCORE must never exceed VDD by 0.3 volts.

FIGURE 24-2: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 27.1 "DC Characteristics: Supply Voltage"** for the full operating ranges of VDD and VDDCORE.

ADDWFC **ADD W and Carry bit to f**

Syntax: ADDWFC f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) + (f) + (C) → dest

Status Affected: N,OV, C, DC, Z

Encoding:

0010	00da	ffff	ffff

Description: Add W, the Carry flag and data memory location, 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in data memory location 'f'.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `ADDWFC REG, 0, 1`

Before Instruction
Carry bit = 1
REG = 02h
W = 4Dh
After Instruction
Carry bit = 0
REG = 02h
W = 50h

ANDLW **AND Literal with W**

Syntax: ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. k → W

Status Affected: N, Z

Encoding:

0000	1011	kkkk	kkkk

Description: The contents of W are ANDed with the 8-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example: `ANDLW 05Fh`

Before Instruction
W = A3h
After Instruction
W = 03h

COMF **Complement f**

Syntax: COMF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $\bar{f} \rightarrow$ dest

Status Affected: N, Z

Encoding:

0001	11da	ffff	ffff

Description: The contents of register 'f' are complemented. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: `COMF REG, 0, 0`

Before Instruction
REG = 13h
After Instruction
REG = 13h
W = ECh

CPFSEQ **Compare f with W, Skip if f = W**

Syntax: CPFSEQ f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) = (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	001a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of W by performing an unsigned subtraction.

If 'f' = W, then the fetched instruction is discarded and a NOP is executed instead, making this a two-cycle instruction.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)

Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    CPFSEQ REG, 0
NEQUAL  :
EQUAL   :
```

Before Instruction
PC Address = HERE
W = ?
REG = ?
After Instruction
If REG = W;
PC = Address (EQUAL)
If REG ≠ W;
PC = Address (NEQUAL)

INCFSZ **Increment f, Skip if 0**

Syntax: INCFSZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest,
skip if result = 0

Status Affected: None

Encoding:

0011	11da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'.

If the result is '0', the next instruction which is already fetched is discarded and a NOP is executed instead, making it a two-cycle instruction.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    INCFSZ   CNT, 1, 0
NZERO   :
ZERO    :
```
Before Instruction
PC = Address (HERE)
After Instruction
CNT = CNT + 1
If CNT = 0;
PC = Address (ZERO)
If CNT ≠ 0;
PC = Address (NZERO)

INFSNZ **Increment f, Skip if not 0**

Syntax: INFSNZ f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest,
skip if result ≠ 0

Status Affected: None

Encoding:

0100	10da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f'.

If the result is not '0', the next instruction which is already fetched is discarded and a NOP is executed instead, making it a two-cycle instruction.

If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.

If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    INFSNZ  REG, 1, 0
ZERO
NZERO
```
Before Instruction
PC = Address (HERE)
After Instruction
REG = REG + 1
If REG ≠ 0;
PC = Address (NZERO)
If REG = 0;
PC = Address (ZERO)

27.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any digital only I/O pin or $\overline{MCLR}$ with respect to V_{SS} (except V_{DD}) ..... -0.3V to 6.0V
Voltage on any combined digital and analog pin with respect to V_{SS} (except V_{DD}) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DDCORE} with respect to V_{SS} ..... -0.3V to 2.75V
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to 3.6V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Maximum output current sunk by any PORTB and PORTC I/O pin ..... 25 mA
Maximum output current sunk by any PORTD, PORTE and PORTJ I/O pin ..... 8 mA
Maximum output current sunk by any PORTA, PORTF, PORTG and PORTH I/O pin ..... 4 mA
Maximum output current sourced by any PORTB and PORTC I/O pin ..... 25 mA
Maximum output current sourced by any PORTD, PORTE and PORTJ I/O pin ..... 8 mA
Maximum output current sourced by any PORTA, PORTF, PORTG and PORTH I/O pin ..... 4 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

† **NOTICE:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

27.2 DC Characteristics: Power-Down and Supply Current PIC18F87J10 Family (Industrial)

PIC18F87J10 Family (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**	
	Power-Down Current (IPD)(1)					
	All devices	27	69	μA	-40°C	VDD = 2.0V(5) (**Sleep** mode)
		43	69	μA	+25°C	
		121	149	μA	+85°C	
	All devices	49	104	μA	-40°C	VDD = 2.5V(5) (**Sleep** mode)
		69	104	μA	+25°C	
		166	184	μA	+85°C	
	All devices	75	203	μA	-40°C	VDD = 3.3V(6) (**Sleep** mode)
		100	203	μA	+25°C	
		140	289	μA	+85°C	

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD;
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

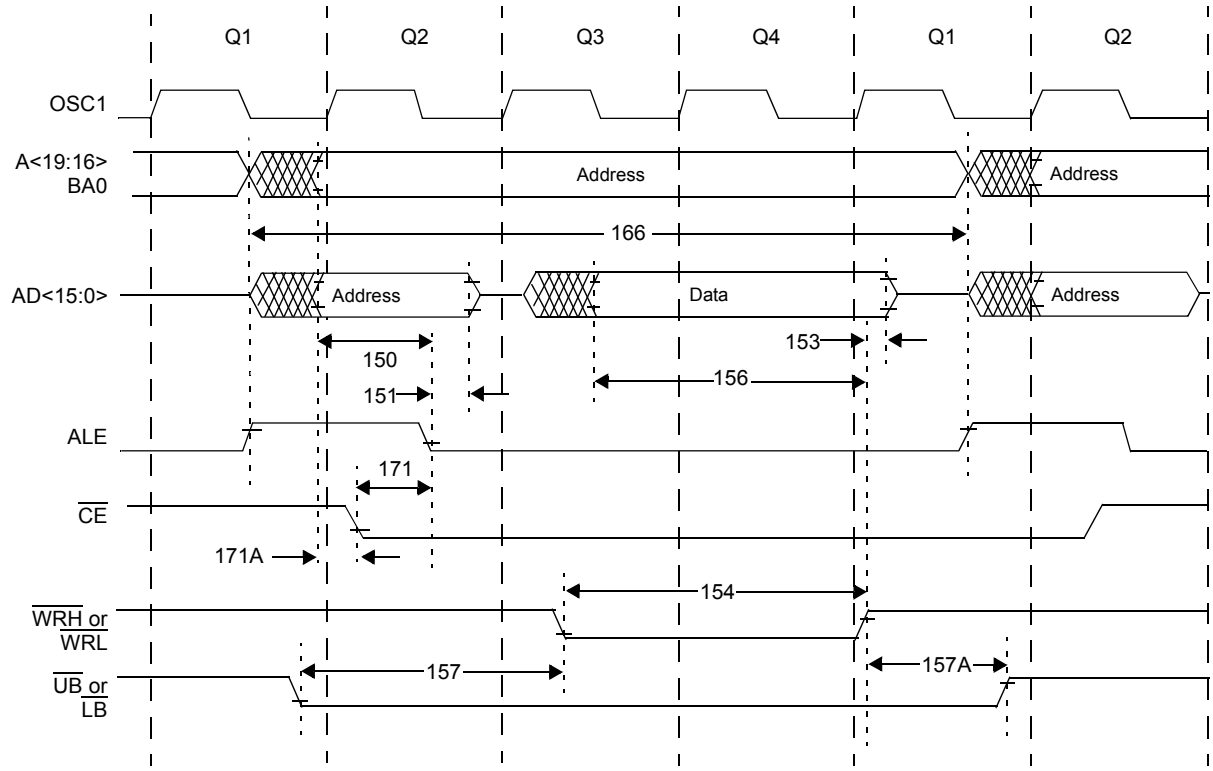
3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kΩ.

4: Standard, low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

5: ENVREG tied to VSS, voltage regulator disabled.

6: ENVREG tied to VDD, voltage regulator enabled.

FIGURE 27-9: PROGRAM MEMORY WRITE TIMING DIAGRAM



Operating Conditions: 2.0V < VCC < 3.6V, -40°C < TA < +125°C unless otherwise stated.

TABLE 27-11: PROGRAM MEMORY WRITE TIMING REQUIREMENTS

Param. No	Symbol	Characteristics	Min	Typ	Max	Units
150	TadV2alL	Address Out Valid to ALE ↓ (address setup time)	0.25 TCY – 10	—	—	ns
151	TalL2adl	ALE ↓ to Address Out Invalid (address hold time)	5	—	—	ns
153	TwrH2adl	$\overline{WRn}$ ↑ to Data Out Invalid (data hold time)	5	—	—	ns
154	TwrL	$\overline{WRn}$ Pulse Width	0.5 TCY – 5	0.5 TCY	—	ns
156	TadV2wrH	Data Valid before $\overline{WRn}$ ↑ (data setup time)	0.5 TCY – 10	—	—	ns
157	TbsV2wrL	Byte Select Valid before $\overline{WRn}$ ↓ (byte select setup time)	0.25 TCY	—	—	ns
157A	TwrH2bsl	$\overline{WRn}$ ↑ to Byte Select Invalid (byte select hold time)	0.125 TCY – 5	—	—	ns
166	TalH2alH	ALE ↑ to ALE ↑ (cycle time)	—	TCY	—	ns
171	TalH2csL	Chip Enable Active to ALE ↓	0.25 TCY – 20	—	—	ns
171A	TubL2oeH	AD Valid to Chip Enable Active	—	—	10	ns

TABLE 27-23: MASTER SSP I²C™ BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock High Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
101	TLOW	Clock Low Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
102	TR	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
103	TF	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
90	TSU:STA	Start Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	Only relevant for Repeated Start condition
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
91	THD:STA	Start Condition Hold Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	After this period, the first clock pulse is generated
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
106	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	ms	
			1 MHz mode(1)	—	—	ns	
107	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	—	—	ns	
92	TSU:STO	Stop Condition Setup Time	100 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			400 kHz mode	2(TOSC)(BRG + 1)	—	ms	
			1 MHz mode(1)	2(TOSC)(BRG + 1)	—	ms	
109	TAA	Output Valid from Clock	100 kHz mode	—	3500	ns	
			400 kHz mode	—	1000	ns	
			1 MHz mode(1)	—	—	ns	
110	TBUF	Bus Free Time	100 kHz mode	4.7	—	ms	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	ms	
			1 MHz mode(1)	—	—	ms	
D102	CB	Bus Capacitive Loading		—	400	pF	

Note 1: Maximum pin capacitance = 10 pF for all I²C™ pins.

2: A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but parameter #107 ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCLx signal. If such a device does stretch the LOW period of the SCLx signal, it must output the next data bit to the SDAx line, parameter #102 + parameter #107 = 1000 + 250 = 1250 ns (for 100 kHz mode), before the SCLx line is released.